

**Preliminary Amendment**

Applicant: Riedl

Filed: September 30, 2005

Docket No.: 1431.131.101/FIN421PCT/US

Title: **DIFFUSION SOLDERED SEMICONDUCTOR DEVICE AND METHOD (As Amended)**

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**IN THE ABSTRACT**

Please replace the Abstract with the following re-written paragraph:

**DIFFUSION SOLDERED SEMICONDUCTOR DEVICE AND METHOD**

The invention relates to a process for the multi-stage production of diffusion-soldered joints for power components with semiconductor chips, the melting points of diffusion-soldering alloys and diffusion-soldered joints being staggered in such a manner that a first melting point of the first diffusion-soldering alloy is lower than a second melting point of the second diffusion-soldering alloy, and the second melting point being lower than a third melting point of a first diffusion-soldered joint of the first diffusion-soldering alloy.